### SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 3.50mm Wire	To Board Connector
CUSTOMER PROD.NO/DWG.NO:	
E&T PROD.NO:	4100K-X02N-XXX
APPROVAL SHEET NO:	
E&T DWG. NO./DOCUMENT:	4100K-X02N-XXX

REV: A1

## PLEASE RETURN TO US ONE COPY OF SPECIFICATION FOR APPROVAL WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES							



ENTERY INDUSTRIAL CO., LTD.
E&T ELECTRONICS (DONG GUAN) CO., LTD.
E&T ELECTRONICS (SU ZHOU) CO., LTD.

Title: Pitch 3.50mm Wire To Board Connector,

	Revised	Title: Pitch3.50mm Wire To Board Connector			
	Max Lee	Title: Fights. Symmi wife to board Connector			
A1	10,18,2011'	This Document Contains Information That Is Proprietary To			
Rev	Rev Description E&T And Should Not Be Used Without Written Permission				
Document No.		Prepared By: Kaz Weng	Date: 10,19'2010		

4100K-X02N-XXX

Checked By:
Approved By:

Date:
Date:
Date:

### GROUP AND TEST SEQUENCE

	Test of Examination		Test Group									
			В	С	D	Е	F	G	Н	I	J	K
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,3	1,3	1,3	1,5	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4				2,4	2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	Insertion Force And Withdrawal Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						2					
13	Resistance To Soldering Heat							2				
14	Steam Aging								2			
15	Salt Spray									3		
16	Temperature Cycling										3	

### PRODUCT SPECIFICATION

#### 1. SCOPE:

This specification covers the 3.50 mm pitch Wire To Board connector series.

### 2. PRODUCT NAME AND PART NUMBER:

Product Name	E&T Part Number
3.50mm Wire To Board Connector	4100K-X02N-XXX

#### 3. RATINGS:

Item	Standard	
Rated Voltage (MAX.)	1400 V	AC/DC
Rated Current (MAX.)	1A	ACIDO
Ambient Temperature Range	-40°C ~ +85°C	

<sup>\*</sup>Including temperature rise in applying electrical current

#### 4.PERFORMANCE:

#### 4- 1 Electrical Performance

	Item Test Condition		Requirement
4-1-1	Contact Resistance	Test Current: 10 mA Max. Test Voltage: 20mV Max Test Method: EIA-364-06B	10 mΩ MAX.
4-1-2 Insulation		Test Voltage: 500V DC. Test Duration: 1 minutes.	Initial: 1000 MΩ Min.
4-1-2	Resistance	Test Method: EIA-364-21C	Final: 500 MΩ Min.
4-1-3	Dielectric Strength	Test Voltage: 3800V AC. Test Time: 60 sec. Test Method: EIA-364-20B	No Breakdown

### 4-2 Mechanical Performance

	Item	Test Condition	Requir	ement
4-2-1	Insertion Force And Withdrawal Force	Test Speed: 25±3 mm/min. Test Method: EIA-364-13B	Insertion Force Withdrawal Force	2.55 kgf (Max) 0.5 kgf (Min)
4-2-2	Terminal / Housing Retention Force	Test Speed: 25mm/min.	1.02kg	f (Min)

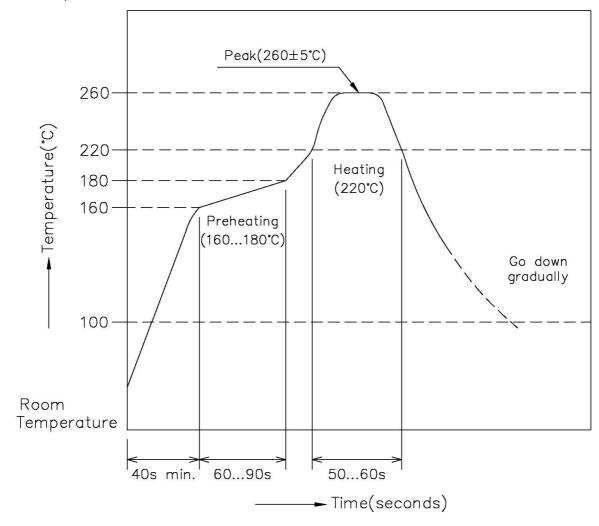
### **4-3 Environmental Performance and Others**

Item		Test Condition	Require	ment
		The contacts of connector shall be subject to 30 cycles of mating and unmating.	Contact Re	sistance
4-3-1	Durability	Test Method: EIA-364-13B	Initial Value	$\leq$ 10 m $\Omega$
			Final Value	$\leq$ 20 m $\Omega$
		Amplitude : 1.5 ₪₪ Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-2	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100mA. Test Method: EIA-364-28D	Contact Resistance	≦20 mΩ
		Tool Method. Elik 66 i 265	Discontinuity	1µsec
4-3-3	Heat	Temperature: 85±2°C Duration: 96 hours	Appearance	No Damage
100	Resistance	e	Contact Resistance	$\leqq 20 \text{ m}\Omega$
4-3-4	Cold	Temperature: -40±2°C Duration: 96 hours	Appearance	No Damage
	Resistance		Contact Resistance	$\leq$ 20 m $\Omega$
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
4-3-5	Humidity	Duration: 96 hours Test Method: EIA-364-31B	Contact Resistance	$\leq$ 20 m $\Omega$
	riairiiaity		Insulation Resistance	≥500MΩ
			Dielectric Strength	Must meet 4-1-3
4-3-6	Solder Ability	Soldering Time : 3±0.5 sec Solder Temperature : 245±5℃ Test Method: EIA-364-52	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes

	Item	Test Condition	Requi	rement
4-3-7	Resistance To Soldering Heat	Soldering Time : $10\pm0.5$ sec Solder Temperature : $260\pm5^{\circ}$ C Test Method: EIA-364-56C	Appearance	No Damage
		Steam Aging Temperature : 98±2℃ Duration: 8 hours Solder Temperature : 245±5℃	Appearance	No Damage
4-3-8	Steam Aging	Soldering Time : 3±0.5 sec Test Method: EIA-364-17B	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-9	Salt Spray	Chamber Temperature : 35±2°C Air Tank Temperature : 47±1°C Salt Solution : 5 ± 0.5% Duration : 48 hours	Appearance	No Damage
	Guit Opiay	Test Method: EIA-364-26B	Contact Resistance	$\leq$ 20 m $\Omega$
4-3-10	Temperature	5 cycles of : a) - 40 $\pm 3^{\circ}$ C 30 minutes b) +25 $\pm 3^{\circ}$ C 30 minutes	Appearance	No Damage
4-3-10	Cycling	c)+ 85 $\pm 2^{\circ}$ C 30 minutes Test Method: EIA-364-31B	Contact Resistance	$\leq$ 20 m $\Omega$

#### INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260±5°C peak shall be 10 seconds maximum.



## Wire To Board Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

### 1. Common Handling Precautions

- Do not expose E&T's wire to board connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's wire to board connector, processing process product and processing product. Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.
- E&T's wire to board connector is not designed for the mating and unmating of the connectors to be performed under the condition of an active electrical circuit. It may cause a spark and product defect if the connectors are mated and unmated in this way.

#### 2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).
- Changing recommended pattern causes problems.

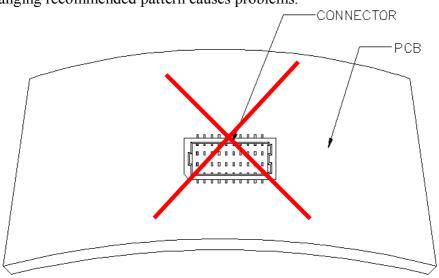


Figure 1.

### 3. Precautions Crimped Terminal Insertion

- Terminal must be inserted horizontally oriented (see figure 2).
- Do not attempt to insert crimped terminal in any other direction. (see figure 2).

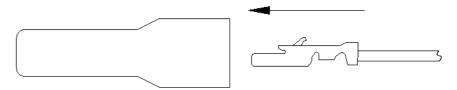
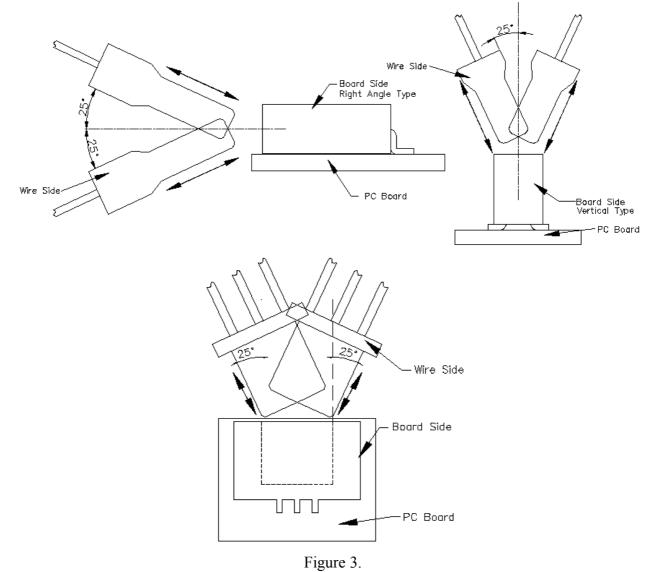


Figure 2.

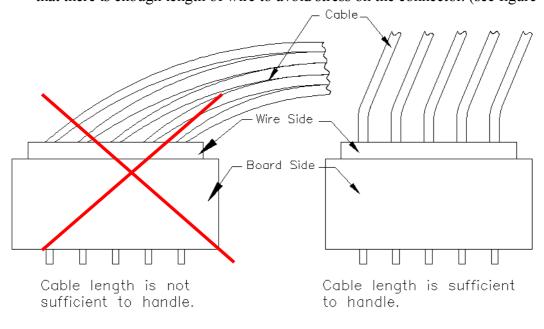
### 4. Precautions When Inserting or Withdrawal Wire To Board

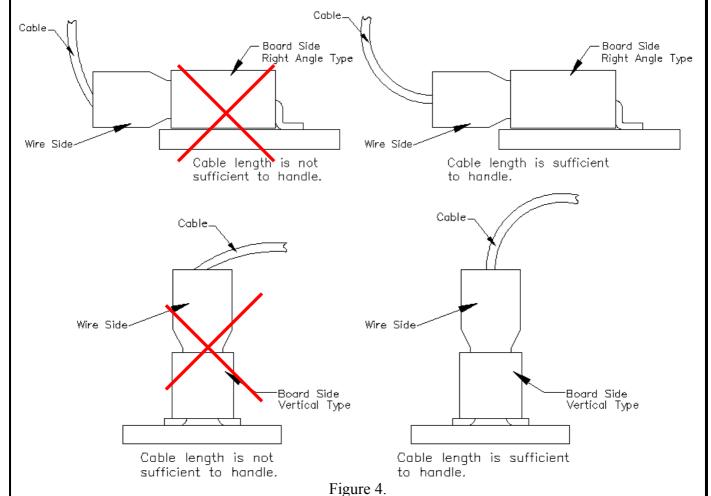
- Do not insert and remove at an angle of 25° or greater. Doing so will cause contact deformation or case damage. (see figure 3).
- Push the wire side connector until firmly closed. At this time, confirm that the wire side connector is mated securely.
- When mounting of connectors, its slant or aberration shall be 3° max.
- Do not insert and remove the connectors when the board side connector is not mounted on the PC board.
- Used Lock type, when removed to connectors, please released positive locks.



### 5. Precautions Cable Assembly

• The cable assembly should not have a constant stress or pulling force applied on it when it is in the mated condition. Therefore, when designing the wire positioning, please ensure that there is enough length of wire to avoid stress on the connector. (see figure 4).





# ENTERY INDUSTRIAL CO., LTD. RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A1	RE201110012 RE201111014	NOV-24-2011	Max	Add Handing Precautions LCP 6130LX Change LCP E130I
Ai	RE201111014 RE201111028	110 1-24-2011	Iviax	Cancel Packaging Spec